

DEVICE FOR USE AS DUAL-SIDED SENSOR PACKAGE

ABSTRACT

A sensor package, and in one embodiment a sensor package for surface mount applications, that comprises a housing and a leadframe with an upper and lower surface for receiving a device thereon. Embodiments of the sensor package comprise a first device secured to the upper surface, and a second device secured to the lower surface so as to place connective pads from each of the first device and the second device proximate to one side of the leadframe. The sensor package further comprises a lead that is positioned in the sensor package in a manner that prevents electrical connection with circuitry that is external of the housing. The lead has an end proximate the side of the leadframe where the connective pads are positioned on the upper and lower surfaces. The end is configured to receive connections, e.g., wirebonds, from the connective pads in a manner connecting the first device and the second device independent of any external connections of the sensor package.

Fig. 1